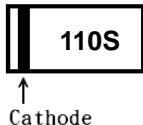


RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

FEATURES

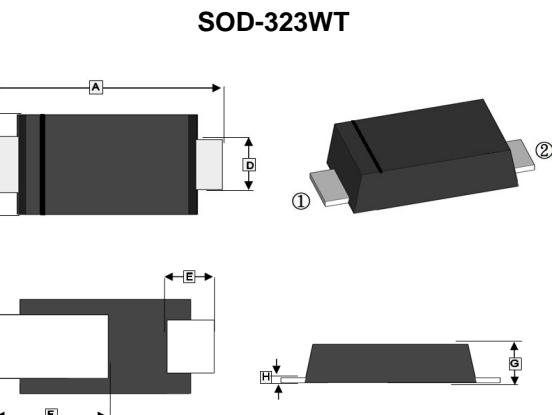
- Low V_F Schottky Barrier Diodes
- Very Low Profile-Typical Height of 0.65 mm
- Low Forward Voltage Drop
- Moisture Sensitivity: Level 1, per J-STD-020
- High Temperature Soldering Guaranteed: 260°C/10s

MARKING



PACKAGE INFORMATION

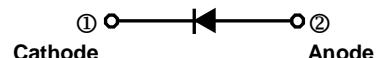
Package	MPQ	Leader Size
SOD-323WT	15K	13 inch



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.30	2.70	E	0.40	0.75
B	0.75	1.00	F	1.10	1.50
C	1.20	1.40	G	0.60	0.73
D	0.55	0.75	H	0.10	0.25

ORDER INFORMATION

Part Number	Type
SM1100WT-C	Lead (Pb)-free and Halogen-free



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise specified.)

Parameter	Symbol	Rating	Unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	100	V
Maximum RMS Voltage	V_{RMS}	70	
Maximum DC Blocking Voltage	V_{DC}	100	
Maximum Average Forward Rectified Current	I_F	1	A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load	I_{FSM}	25	A
Maximum Instantaneous Forward Voltage @ $I_F=1\text{A}$	V_F	0.8	V
Maximum DC Reverse Current @ Rated DC Blocking Voltage	I_R	20	uA
Typical Junction Capacitance @ 4V, 1MHz	C_J	28	pF
Typical Thermal Resistance from Junction-Ambient ¹	$R_{\theta JA}$	82	°C/W
Typical Thermal Resistance from Junction-Lead ¹	$R_{\theta JL}$	6	
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55~150	°C

Notes:

1. The thermal resistance from junction to ambient or lead, mounted on P.C.B with 5x5mm copper pads, 2OZ, FR4 PCB.

RATINGS AND CHARACTERISTIC CURVES

Figure 1. Forward Current Derating Curve

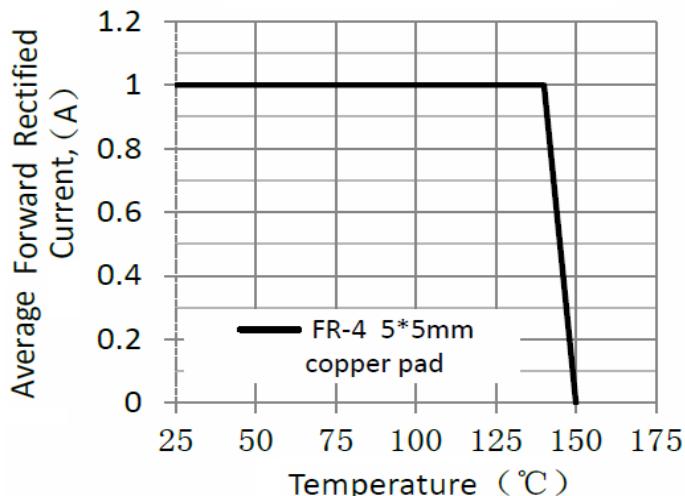


Figure 3. Typical Reverse Characteristics

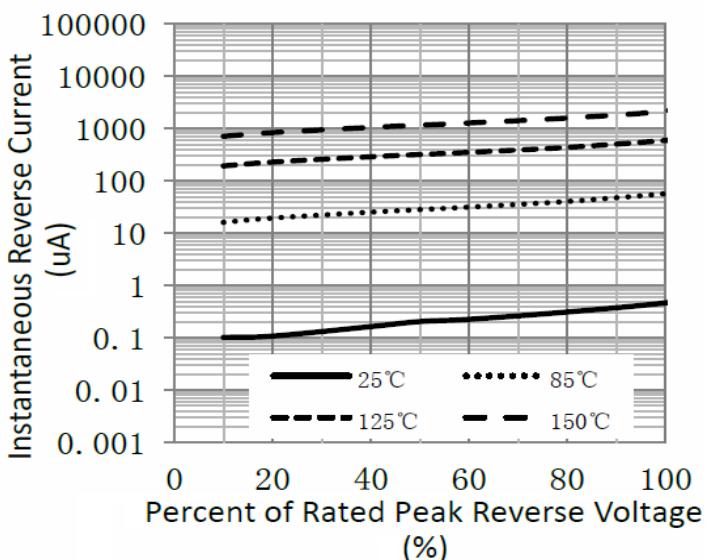


Figure 5. Maximum Non-Repetitive Peak Forward Surge Current

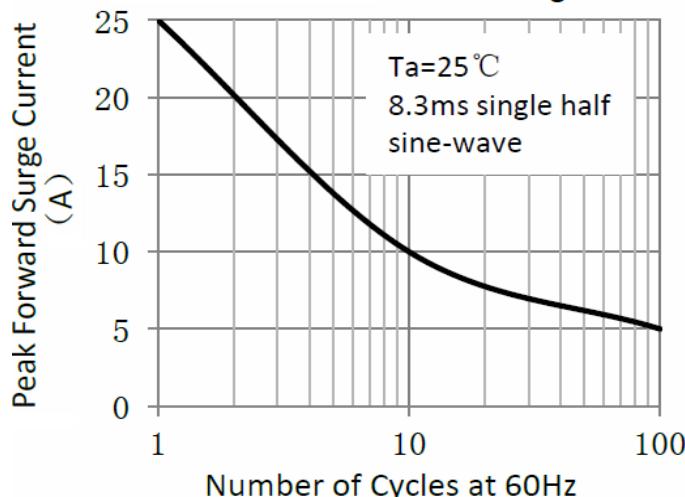


Figure 2. Typical Instantaneous Forward Characteristics

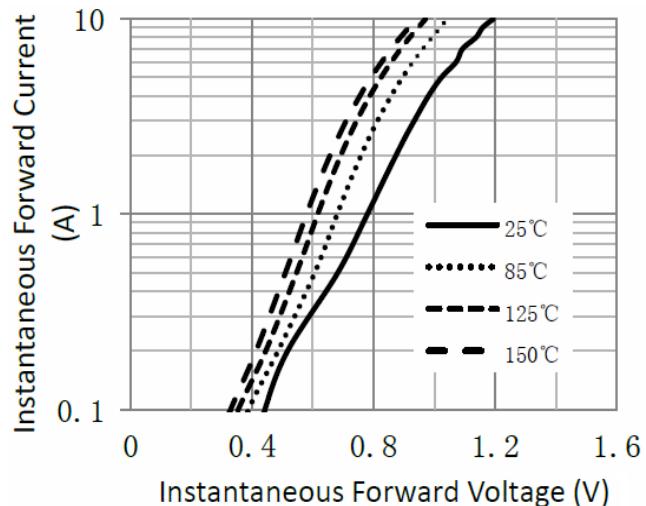


Figure 4. Typical Junction Capacitance

